Dexerials

Technical Data Sheet

Adhesive transfer tapes for FPC T4100 series

Features

- Ideal for bonding FPC materials such as Polyimide, Stainless steel plate (SUS304), Glass epoxy, etc.
- Adhesive and release paper can resist high temperature of the solder reflow process.
- The thin type T4103 adhesive layer makes it ideal for miniaturizing products.

Structure

Product name	T4100	T4103	T4100W *2
Main component	Acrylic	Acrylic	Acrylic
Carrier	Non-carrier	Non-carrier	Non-carrier
Color	Translucent	Translucent	Translucent
Adhesive thickness (μm)	About 50	About 25	About 50
Release paper thickness (μm)	About 100	About 100	About 100+110
Bonding strength (N/20mm) *1	9	7	9
St'd size (width & length)	500mm × 100m	500mm × 100m	500mm × 100m

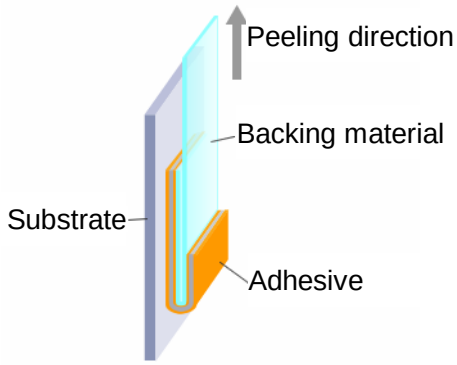
*1 180° peeling strength （Substrate: Polyimide)
*2 T4100W is double side release papers type

Suitable use

- Ideal for bonding stiffener to FPC and bonding nameplates to plastics and metal materials

1.Bonding strength (180° peeling)

＜Test piece condition＞
Substrate: Polyimide
Tape width: 20mm
Bonding condition: One stroke with 2-kg roller
Measuring condition: 23℃±5℃ 60%±20%RH
Peeling speed: 300mm/min
Backing material: 25μmPET
[Left at RT for one hour before measurement]



＜180° peeling strength test＞

＜Results＞ （N/20mm）

Product name	T4100	T4103
Peeling strength	9	7

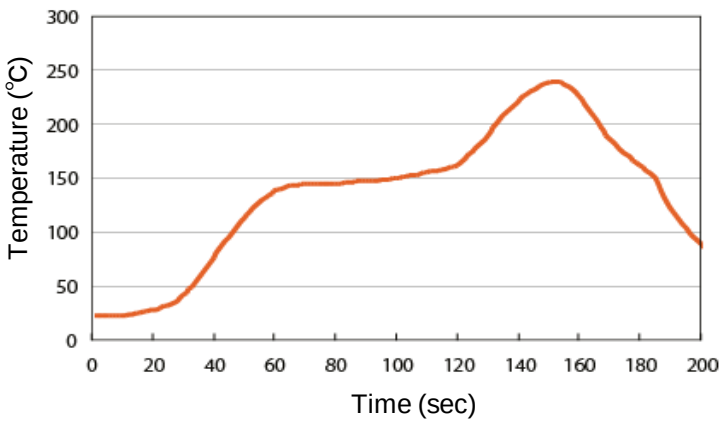
2. Bonding strength before and after reflow (180° peeling)

＜Test piece condition＞
Tape width: 20mm
Bonding condition: One stroke with 2-kg roller
Measuring condition: 23℃±5℃ 60%±20%RH
Peeling speed: 300mm/min
Backing material: 25μm Polyimide
[Attach adhesive tape to polyimide and reflow without removing release paper before measurement under the following conditions]

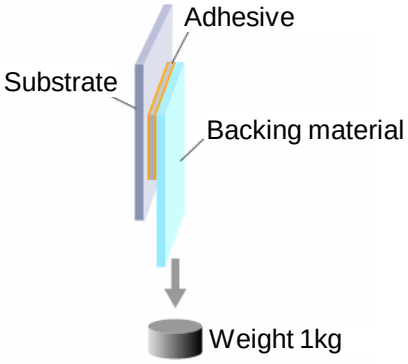
＜Results＞ （N/20mm）

Product name		T4100	T4103
Peeling strength	Before reflow	9	7
	After reflow	9	7

＜Profile of lead free solder reflow process＞



3. Holding power under each temperature

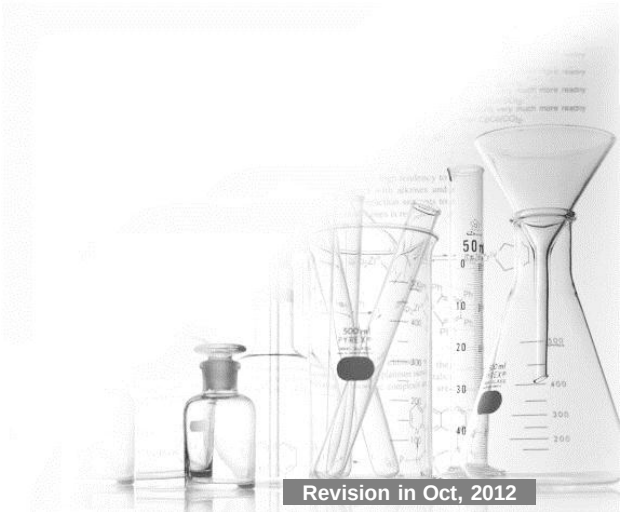


＜Holding power test＞

＜Test piece condition＞
Substrate：Stainless steel plate (SUS304)
Bonding area：25mm × 25mm
Bonding condition：One stroke with 2-kg roller
Backing material：25μm Polyimide
[Left at RT for one hour and then at each temperature for 30 minutes before measurement]
[Creep length after one hour application of 1-kg load]

＜Results＞ （mm）

Temperature	23℃	40℃	60℃	80℃	100℃
T4100	0	0.1	0.3	0.5	0.6
T4103	0	0	0.2	0.3	0.3



Revision in Oct, 2012

Note on the characteristic data given— Data on the characteristics of the products described in this catalog are based on the results of evaluations carried out by the company. This does not guarantee that the characteristics of the product conform with your usage environment. Before use, review the usage conditions based on evaluation data obtained from the equipment and substrates actually used.

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